

AMENDMENTS TO THE CLAIMS

1. (Withdrawn) A cross-linked polyimide produced by polycondensing (a) tetramine(s), (a) tetracarboxylic dianhydride(s) and (an) aromatic diamine(s) in the presence of a catalyst, which cross-linked polyimide has a dielectric constant of not more than 2.7.

2. (Withdrawn) The polyimide according to claim 1, wherein said tetramine(s) is(are) (an) aromatic tetramine(s).

3. (Withdrawn) The polyimide according to claim 1, wherein said aromatic tetramine(s) is(are) at least one selected from the group consisting of bis(3,5-diaminobenzoyl)--1,4-piperazine, bis(3,5-diaminobenzoyl)-4,4'-diiminodiphenylether, bis-(3,5-diaminophenyl)-2,2'-dioxazol-4,4'-diphenylsulfone, bis(3,5-diaminophenyl)-2,2'-dioxazol-4,4'-biphenyl, 2,7-diamino-9,9'-(bis-4-aminophenyl)fluorene and bis(3,5-diaminobenzoyl)-1,4-diaminobenzene.

4. (Withdrawn) The polyimide according to claim 1, which comprises a diaminosiloxane as a part of diamine component.

5. (Withdrawn) The polyimide according to claim 1, which was produced by sequential reactions comprising polycondensing a tetramine, a tetracarboxylic dianhydride and an aromatic diamine in the presence of the catalyst to generate a polyimide oligomer, and then reacting the polyimide oligomer, a tetracarboxylic dianhydride and an aromatic diamine.

6. (Withdrawn) The polyimide according to claim 5, which was produced such that the difference between the number of moles of said tetracarboxylic dianhydride and the number of moles of said aromatic diamine, which are reacted with said tetramine is 2 moles per 1 mole of said tetramine.

7. (Withdrawn) The polyimide according to claim 6, which was produced by a process comprising polycondensing said tetramine, 4 moles of said tetracarboxylic dianhydride and 4 moles of said aromatic diamine per 1 mole of said tetramine to generate said polyimide

oligomer, and then reacting the polyimide oligomer, 4 moles of the tetracarboxylic dianhydride and 2 moles of the aromatic diamine.

8. (Withdrawn) The polyimide according to claim 6, which was produced by a process comprising polycondensing said tetramine, 8 moles of said tetracarboxylic dianhydride and 4 moles of said aromatic diamine per 1 mole of said tetramine to generate said polyimide oligomer, and then reacting the polyimide oligomer, 2 moles of tetracarboxylic dianhydride and 4 moles of aromatic diamine.

9. (Withdrawn) The polyimide according to claim 1, which has a weight average molecular weight based on polystyrene of 15,000 to 300,000.

10. (Withdrawn) The polyimide according to claim 1, which has a dielectric constant of 1.9 to 2.2.

11. (Currently Amended) A process for producing a composition containing a cross-linked polyimide, comprising polycondensing (a) tetramine(s), (a) tetracarboxylic dianhydride(s) and (an) aromatic diamine(s) in a polar solvent containing toluene or xylene in the presence of a catalyst under heat,

said polycondensation yielding said cross-linked polyimide, said cross-linked polyimide having a dielectric constant of not more than 2.7.

12. (Original) The process according to claim 11, wherein said tetramine(s) is(are) (an) aromatic tetramine(s).

13. (Currently amended) The process according to claim 12, wherein said aromatic tetramine(s) is(are) at least one selected from the group consisting of bis(3,5-diaminobenzoyl)-1,4-piperazine, bis(3,5-diaminobenzoyl)-4,4'-diiminodiphenylether, bis(3,5-diaminobenzoyl)-4,4'-diiminodiphenylether, bis-(3,5-diaminophenyl)-2,2'-dioxazol-4,4'-diphenylsulfone, bis(3,5-diaminophenyl)-2,2'-dioxazol-4,4'-biphenyl, 2,7-diamino-9,9'-(bis-4-aminophenyl)fluorene and

bis(3,5-diaminobenzoyl)-1,4-diaminobenzene.

14. (previously presented) The process according to claim 11, wherein a diaminosiloxane is contained as a part of diamine component.

15. (previously presented) The process according to claim 11, wherein said catalyst is a binary catalyst comprising (an) acid(s) selected from the group consisting of oxalic acid, malonic acid, formic acid and pyruvic acid, and a base, or a binary catalyst comprising a lactone and a base.

16. (Original) The process according to claim 15, wherein said catalyst is a binary catalyst comprising oxalic acid and a base, or a binary catalyst comprising a lactone and a base.

17. (previously presented) The process according to claim 16, wherein reactants are directly imidized in the presence of said binary catalyst at 160°C to 200°C.

18. (previously presented) The process according to claim 11, by sequential reactions, comprising polycondensing the tetramine, the tetracarboxylic dianhydride and the aromatic diamine in the presence of the catalyst to generate a polyimide oligomer, and then reacting the polyimide oligomer with tetracarboxylic dianhydride and aromatic diamine.

19. (Original) The process according to claim 17, wherein the difference between the number of moles of said tetracarboxylic dianhydride and the number of moles of said aromatic diamine, which are reacted with said tetramine is 2 moles per 1 mole of said tetramine.

20. (Original) The process according to claim 19, wherein said tetramine, 4 moles of said tetracarboxylic dianhydride and 4 moles of said aromatic diamine are reacted per 1 mole of said tetramine to generate said polyimide oligomer, and then reacting the polyimide oligomer, 4 moles of the tetracarboxylic dianhydride and 2 moles of the aromatic diamine.

21. (Original) The process according to claim 19, wherein said tetramine, 8 moles of said tetracarboxylic dianhydride and 4 moles of said aromatic diamine are reacted per 1 mole of said tetramine to generate said polyimide oligomer, and then reacting the polyimide oligomer, 2 moles of the tetracarboxylic dianhydride and 4 moles of the aromatic diamine.

22. (previously presented) A process for producing a cross-linked polyimide composition, comprising adding (a) tetracarboxylic dianhydride(s) and (an) aromatic diamine(s) to the polyimide composition produced by the process according to claim 11, mixing the mixture and polycondensing components in the mixture.

23. (previously presented) A process for producing a cross-linked polyimide composition comprising a linear polyimide, said method comprising forming said linear polyimide by carrying out said process according to claim 11 without said tetramine(s).

24. (previously presented) A cross-linked polyimide composition produced by the process according to claim 11.

25. (Original) The polyimide composition according to claim 24, wherein the cross-linked polyimide in said polyimide composition has a weight average molecular weight based on polystyrene of 15,000 to 300,000.

26. (previously presented) The cross-linked polyimide composition according to claim 24, further comprising a linear polyimide produced by the same process as the process according to claim 11 except that said tetramine is not used, and which composition is in the form of liquid at room temperature.

27. (previously presented) A photosensitive cross-linked polyimide composition, further comprising a photoacid generator in said composition according to claim 24.

28. (Withdrawn) A process for producing a patterned polyimide film, comprising

casting a solution of said photosensitive cross-linked polyimide composition according to claim 27 on a substrate, heating the cast composition at 60°C to 90°C to obtain a film, irradiating the film through a mask, and etching the resultant with an alkaline solution to form a positive image.

29. (Withdrawn) The patterned polyimide film produced by the process according to claim 28.

30. (Withdrawn) An electrical or electronic equipment or a part thereof, which comprises an insulation material, insulating substrate or protection material, that contains said cross-linked polyimide according to claim 1.

31. (Withdrawn) The electrical or electronic equipment or a part thereof according to claim 30, wherein said cross-linked polyimide is used as (1) an interlayer insulation film between semiconductor elements, (2) a laminate sheet, multilayer circuit substrate or a substrate of a flexible copper-clad plate, or (3) a semiconductor chip-coating film.

32. (Withdrawn) The electrical or electronic equipment or a part thereof according to claim 31, wherein said semiconductor chip-coating film is a passivation film,  $\alpha$ -ray-shielding film or buffer coat film.

33. (Withdrawn) The electrical or electronic equipment or a part thereof according claim 30, wherein said cross-linked polyimide is a positive-type photosensitive polyimide containing a photoacid generator, and wherein said insulation material or protection material is formed by photolithography.

34. (Withdrawn) The electrical or electronic equipment or a part thereof according to claim 30, wherein said insulation material or protection material is formed by screen printing.

35. (Withdrawn) The electrical or electronic equipment or a part thereof according to claim 30, wherein said cross-linked polyimide comprises anionic group-containing units, and

wherein said insulation material or protection material is formed by electrodeposition.

36. (Withdrawn) The electrical or electronic equipment or a part thereof according to claim 35, wherein group which becomes an anion in aqueous solution is carboxylic group or a salt thereof.